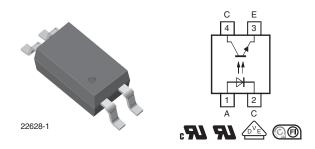


Optocoupler, Phototransistor Output, Single Channel, Half Pitch Mini-Flat Package



DESCRIPTION

The TCMT110. series consist of a phototransistor optically coupled to a gallium arsenide infrared-emitting diode in a 4 pin package.

The elements are mounted on one leadframe providing a fixed distance between input and output for highest safety requirements.

FEATURES

- Low profile package (half pitch)
- AC isolation test voltage 3750 V_{RMS}
- Low coupling capacitance of typical 0.3 pF
- Current transfer ratio (CTR) selected into groups
- Low temperature coefficient of CTR
- Low temperature coefficient of CT
- Wide ambient temperature range
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



- Programmable logic controllers
- Modems
- · Answering machines
- · General applications

AGENCY APPROVALS

- UL1577, file no. E76222, double protection
- cUL component acceptance service no. 5A, double protection
- DIN EN 60747-5-5 (VDE 0884-5)
- FIMKO: FI EN 60950-1:2006
- BSI: BS EN60065:2002 BS EN60950-1:2006
- CQC GB 8898-2011, GB 4943.1-2011 (suitable for installation altitude below 2000 m)

ORDERING	INFORM	ATION								
Т	С	М	Т	1	1	0	#		SSOP-4	
			PART N	IUMBER				-	7.21 mm	-
AGENCY					C	TR (%)				
CERTIFIED/ PACKAGE	5 mA	5 mA 10 mA 5 mA								
UL, cUL, FIMKO, BSI, VDE	50 to 600	40 to 80	63 to 125	100 to 200	160 to 320	50 to 150	100 to 300	80 to 160	130 to 260	200 to 400
SSOP-4	TCMT1100	TCMT1101	TCMT1102	TCMT1103	TCMT1104	TCMT1105	TCMT1106	TCMT1107, TCMT1107T3 ⁽¹⁾	TCMT1108	TCMT1109

Notes

- · Available only on tape and reel
- (1) Product is rotated 180° in tape and reel cavity



ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)							
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT			
INPUT							
Reverse voltage		V _R	6	V			
Forward current		I _F	60	mA			
Forward surge current	t _p ≤ 10 μs	I _{FSM}	1.5	Α			
Power dissipation		P _{diss}	100	mW			
Junction temperature		T _j	125	°C			
OUTPUT							
Collector emitter voltage		V_{CEO}	70	V			
Emitter collector voltage		V _{ECO}	7	V			
Collector current		I _C	50	mA			
Collector peak current	$t_p/T = 0.5, t_p \le 10 \text{ ms}$	I _{CM}	100	mA			
Power dissipation		P _{diss}	150	mW			
Junction temperature		Tj	125	°C			
COUPLER							
AC isolation test voltage (RMS)	Related to standard climate 23/50 DIN 50014	$V_{\rm ISO}$	3750	V _{RMS}			
Total power dissipation		P _{tot}	250	mW			
Operating ambient temperature range		T _{amb}	-40 to +100	°C			
Storage temperature range		T _{stg}	-40 to +125	°C			
Soldering temperature (1)		T _{sld}	260	°C			

Notes

- Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability
- (1) Refer to reflow profile for soldering conditions for surface mounted devices. Also refer to "Assembly Instructions" (www.vishay.com/doc?80054)

ELECTRICAL CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)							
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT	
INPUT							
Forward voltage	$I_F = 50 \text{ mA}$	V _F	-	1.35	1.6	V	
Junction capacitance	$V_R = 0$, $f = 1$ MHz	C _j	-	8		pF	
OUTPUT							
Collector emitter voltage	I _C = 100 μA	V_{CEO}	70	-	-	V	
Emitter collector voltage	I _E = 100 μA	V _{ECO}	7	-	-	V	
Collector dark current	$V_{CE} = 20 \text{ V}, I_F = 0 \text{ A}$	I _{CEO}	-	-	100	nA	
COUPLER							
Collector emitter saturation voltage	$I_F = 10 \text{ mA}, I_C = 1 \text{ mA}$	V _{CEsat}	-	-	0.3	V	
Cut-off frequency	V_{CE} = 5 V, I_F = 10 mA, R_L = 100 Ω	f _c	-	100	-	kHz	
Coupling capacitance	f = 1 MHz	C _k	-	0.3	-	pF	

Note

 Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements



CURRENT TRANSFER RATIO (T _{amb} = 25 °C, unless otherwise specified)								
PARAMETER	TEST CONDITION	PART	SYMBOL	MIN.	TYP.	MAX.	UNIT	
	$V_{CE} = 5 \text{ V}, I_F = 5 \text{ mA}$	TCMT1100	CTR	50	-	600	%	
	V _{CE} = 5 V, I _F = 10 mA	TCMT1101	CTR	40	-	80	%	
		TCMT1102	CTR	63	-	125	%	
I _O /I _F		TCMT1103	CTR	100	1	200	%	
		TCMT1104	CTR	160	-	320	%	
	V _{CE} = 5 V, I _F = 5 mA	TCMT1105	CTR	50	ı	150	%	
		TCMT1106	CTR	100	ı	300	%	
		TCMT1107	CTR	80	-	160	%	
		TCMT1108	CTR	130	-	260	%	
		TCMT1109	CTR	200	-	400	%	

SWITCHING CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Delay time	$V_S = 5 \text{ V}, I_C = 2 \text{ mA}, R_L = 100 \Omega$, (see figure 1)	t _d	-	4.0	-	μs
Rise time	$V_S = 5 \text{ V}, I_C = 2 \text{ mA}, R_L = 100 \Omega$, (see figure 1)	t _r	-	5.5	-	μs
Fall time	$V_S = 5 \text{ V}, I_C = 2 \text{ mA}, R_L = 100 \Omega$, (see figure 1)	t _f	-	7.0	-	μs
Storage time	$V_S = 5 \text{ V}, I_C = 2 \text{ mA}, R_L = 100 \Omega$, (see figure 1)	t _s	-	1.5	-	μs
Turn-on time	$V_S = 5 \text{ V}, I_C = 2 \text{ mA}, R_L = 100 \Omega$, (see figure 1)	t _{on}	-	9.5	-	μs
Turn-off time	$V_S = 5 \text{ V}, I_C = 2 \text{ mA}, R_L = 100 \Omega$, (see figure 1)	t _{off}	-	8.5	-	μs
Turn-on time	$V_S = 5 \text{ V}, I_F = 10 \text{ mA}, R_L = 1 \text{ k}\Omega, \text{ (see figure 2)}$	t _{on}	-	3.0	-	μs
Turn-off time	$V_S = 5 \text{ V}, I_F = 10 \text{ mA}, R_L = 1 \text{ k}\Omega$, (see figure 2)	t _{off}	-	20.0	-	μs

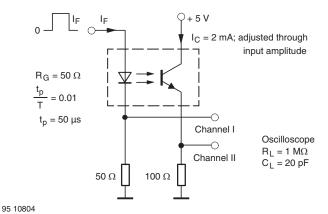


Fig. 1 - Test Circuit, Non-Saturated Operation

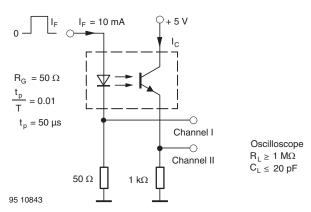


Fig. 2 - Test Circuit, Saturated Operation

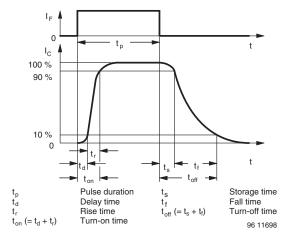


Fig. 3 - Switching Times



PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Climatic classification	According to IEC 68 part 1		40 / 110 / 21	
Pollution degree	According to DIN VDE 0109		2	
Comparative tracking index	Insulation group IIIa	CTI	175	
Maximum rated withstanding isolation voltage	According to UL1577, t = 1 min	V _{ISO}	3750	V _{RMS}
Maximum transient isolation voltage	According to DIN EN 60747-5-5	V _{IOTM}	6000	V _{peak}
Maximum repetitive peak isolation voltage	According to DIN EN 60747-5-5	V _{IORM}	707	V _{peak}
	T _{amb} = 25 °C, V _{IO} = 500 V		≥ 10 ¹²	Ω
Isolation resistance	T _{amb} = 100 °C, V _{IO} = 500 V	R _{IO}	≥ 10 ¹¹	
	$T_{amb} = T_S$, $V_{IO} = 500 \text{ V}$		≥ 10 ⁹	
Output safety power		P _{SO}	350	mW
Input safety current		I _{SI}	150	mA
Input safety temperature		T _S	175	°C
Creepage distance			≥ 5	mm
Clearance distance			≥ 5	mm
Insulation thickness		DTI	≥ 0.4	mm
Input to output test voltage, method B	V_{IORM} x 1.875 = V_{PR} , 100 % production test with t_M = 1 s, partial discharge < 5 pC	V _{PR}	1326	V _{peak}
Input to output test voltage, method A	V_{IORM} x 1.6 = V_{PR} , 100 % sample test with t_M = 10 s, partial discharge < 5 pC	V_{PR}	1132	V _{peak}

TYPICAL CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

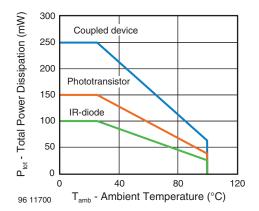


Fig. 4 - Total Power Dissipation vs. Ambient Temperature

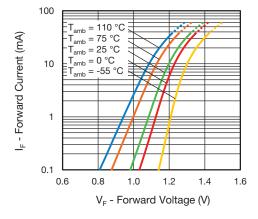


Fig. 5 - Forward Voltage vs. Forward Current

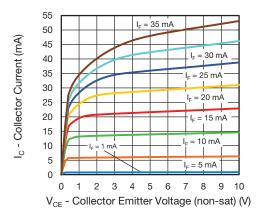


Fig. 6 - Collector Current vs. Collector Emitter Voltage

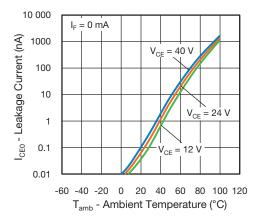


Fig. 7 - Leakage Current vs. Ambient Temperature

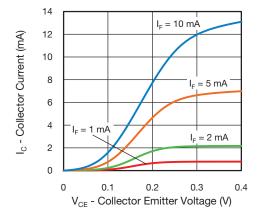


Fig. 8 - Collector Current vs. Collector Emitter Voltage

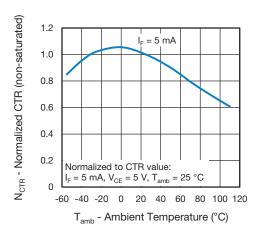


Fig. 9 - Normalized Current Transfer Ratio (non-saturated) vs.

Ambient Temperature

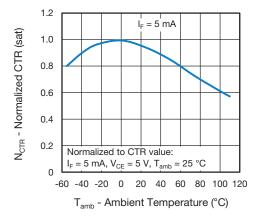


Fig. 10 - Normalized Current Transfer Ratio (saturated) vs.
Ambient Temperature

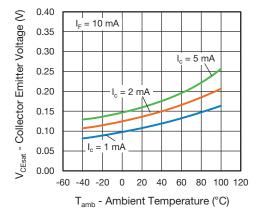


Fig. 11 - Collector Emitter Voltage vs. Ambient Temperature

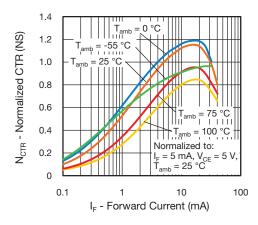


Fig. 12 - Normalized CTR (non-saturated) vs. Forward Current

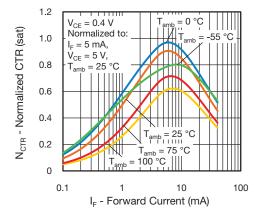


Fig. 13 - Normalized CTR (saturated) vs. Forward Current

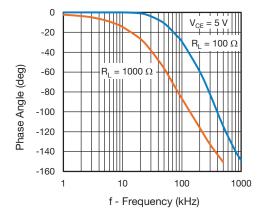


Fig. 14 - F_{CTR} vs. Phase Angle

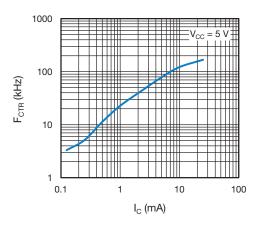


Fig. 15 - F_{CTR} vs. Collector Current

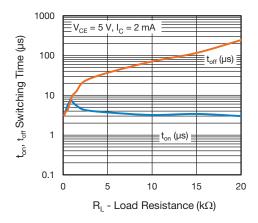
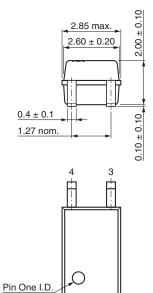
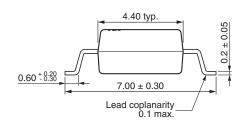


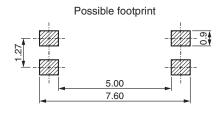
Fig. 16 - Switching Time vs. Load Resistance



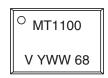
PACKAGE DIMENSIONS in millimeters



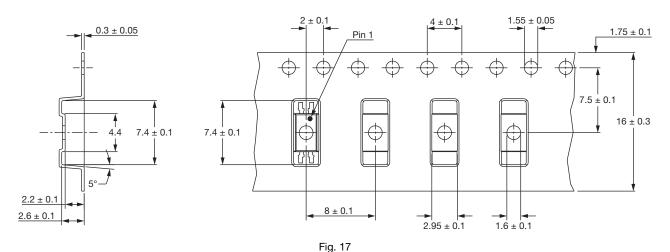




PACKAGE MARKING (example)



TAPE AND REEL PACKAGING in millimeters





SOLDER PROFILES

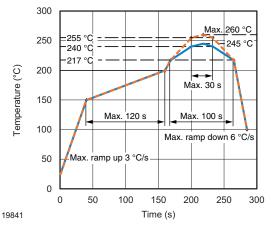


Fig. 18 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020 for SMD Devices

HANDLING AND STORAGE CONDITIONS

ESD level: HBM class 2 Floor life: unlimited

Conditions: T_{amb} < 30 °C, RH < 85 %

Moisture sensitivity level 1, according to J-STD-020



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